

LP2305BLT1G

20V P-Channel Power MOSFET

1. FEATURES

- Low thermal impedance.
- Fast switching speed.
- We declare that the material of product compliance with RoHS requirements and Halogen Free.

2. APPLICATIONS

- Power Tools
- DC-DC conversion
- Motor Control

3. DEVICE MARKING AND RESISTOR VALUES

Device	Marking	Shipping
LP2305BLT1G	P5B	3000/Tape&Reel

4. MAXIMUM RATINGS

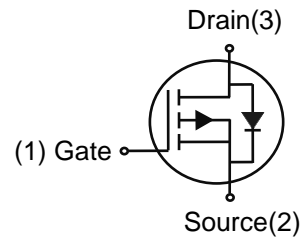
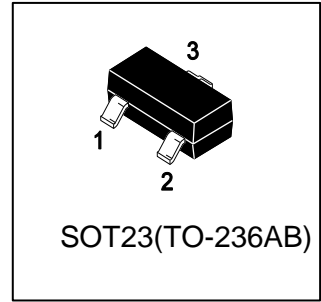
Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current($V_{GS} = -4.5$ V)	I_D	$T_A = 25\text{ }^\circ\text{C}$	-3
		$T_A = 100\text{ }^\circ\text{C}$	-1.9
Pulsed Drain Current ^(Note 2) ; Single Pulse; $t_p \leq 10\text{ }\mu\text{s}$	I_{DM}	-12	A
Avalanche Current	I_{AS}	-9	A
Avalanche Energy($L = 0.1\text{ mH}$)	E_{AS}	4	mJ
Power Dissipation ^(Note 1)	P_D	$T_A = 25\text{ }^\circ\text{C}$	0.69
		$T_A = 100\text{ }^\circ\text{C}$	0.28
Operating Junction and Storage Temperature	T_j, T_{stg}	-55~+150	$^\circ\text{C}$

5. THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Thermal Resistance, Junction-Ambient ^(Note 1)	$R_{\theta JA}$	180	$^\circ\text{C/W}$

Note:1.Surface mounted on "1.5in x 1.5in" FR4 board using 1*1 in pad, 2 oz Cu.

2.Pulse width limited by maximum junction temperature.



6. ELECTRICAL CHARACTERISTICS($T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Static Characteristics					
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$)	$V_{(BR)DSS}$	-20	-	-	V
Gate-Source Threshold Voltage ($V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$)	$V_{GS(th)}$	-0.4	-0.6	-1	V
Zero Gate Voltage Drain Current ($V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$)	I_{DSS}	-	-	-1	μA
Gate-Source Leakage Current ($V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$)	I_{GSS}	-	-	± 100	nA
Drain-Source On-State Resistance ^(Note 3) ($V_{GS} = -4.5\text{ V}, I_D = -3.5\text{ A}$) ($V_{GS} = -2.5\text{ V}, I_D = -3\text{ A}$)	$R_{DS(on)}$	-	46 57	49 65	m Ω
Dynamic Characteristics					
Input Capacitance	$(V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz})$	C_{iss}	-	420	pF
Output Capacitance		C_{oss}	-	64	
Reverse Transfer Capacitance		C_{rss}	-	56	
Total Gate Charge	$(V_{DS} = -10\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -3.5\text{ A})$	Q_g	-	5.7	nC
Gate-Source Charge		Q_{gs}	-	1.2	
Gate-Drain Charge		Q_{gd}	-	1.8	
Turn-On Delay Time	$(V_{DS} = -10\text{ V}, I_D = -3.5\text{ A}, V_{GS} = -4.5\text{ V}, R_G = 3\text{ }\Omega)$	$t_{d(on)}$	-	5.5	ns
Rise Time		t_r	-	8.5	
Turn-Off Delay Time		$t_{d(off)}$	-	37	
Fall Time		t_f	-	20	
Gate Resistance ($V_{DS} = 0\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$)	R_G	-	15	-	Ω
Diode Characteristics					
Diode Continuous Current $T_A = 25\text{ }^\circ\text{C}$	I_S	-	-	-0.8	A
Diode Plused Current, $t_p \leq 10\text{ }\mu\text{s}, T_A = 25\text{ }^\circ\text{C}$	I_{SM}	-	-	-3.2	A
Diode Forward Voltage ($I_S = -4.5\text{ A}, V_{GS} = 0\text{ V}$)	V_{SD}	-	-0.9	-1.2	V
Reverse Recovery Time ($V_R = -10\text{ V}, I_F = -3.5\text{ A}, di_F/dt = -70\text{ A}/\mu\text{s}$)	t_{rr}	-	47	-	ns
Reverse Recovery Charge ($V_R = -10\text{ V}, I_F = -3.5\text{ A}, di_F/dt = -70\text{ A}/\mu\text{s}$)	Q_{rr}	-	17	-	nC
Reverse Recovery Current ($V_R = -10\text{ V}, I_F = -3.5\text{ A}, di_F/dt = -70\text{ A}/\mu\text{s}$)	I_{rrm}	-	-0.67	-	A

 3. Pulse test: $PW \leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

7. ELECTRICAL CHARACTERISTICS CURVES

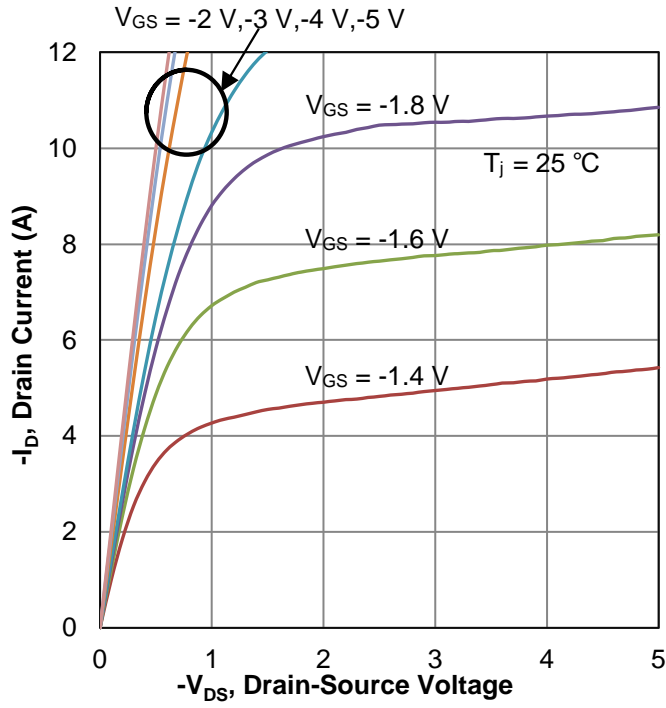


Figure 1. $-I_D$ vs. $-V_{DS}$

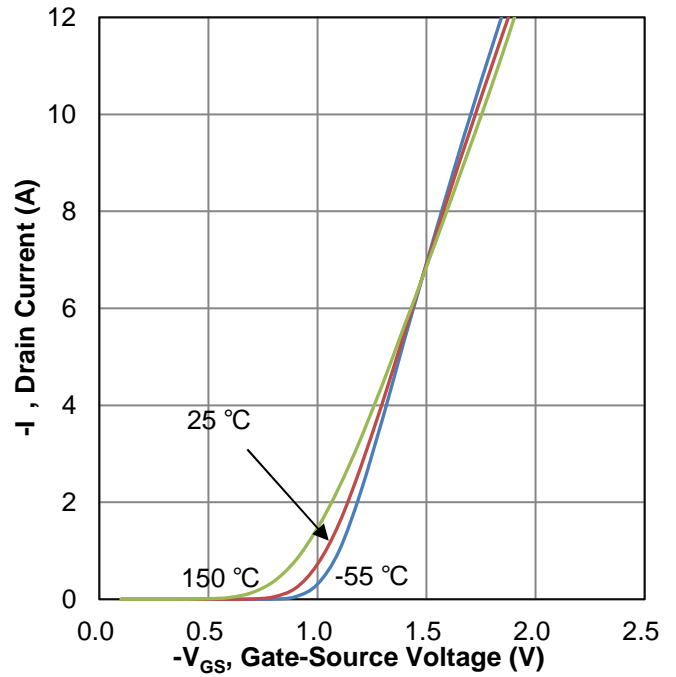


Figure 2. $-I_D$ vs. $-V_{GS}$

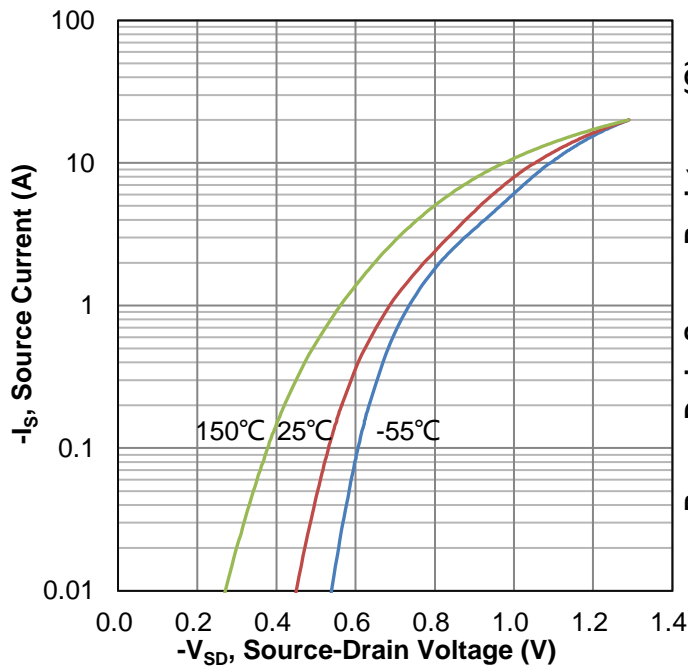


Figure 3. $-I_S$ vs. $-V_{SD}$

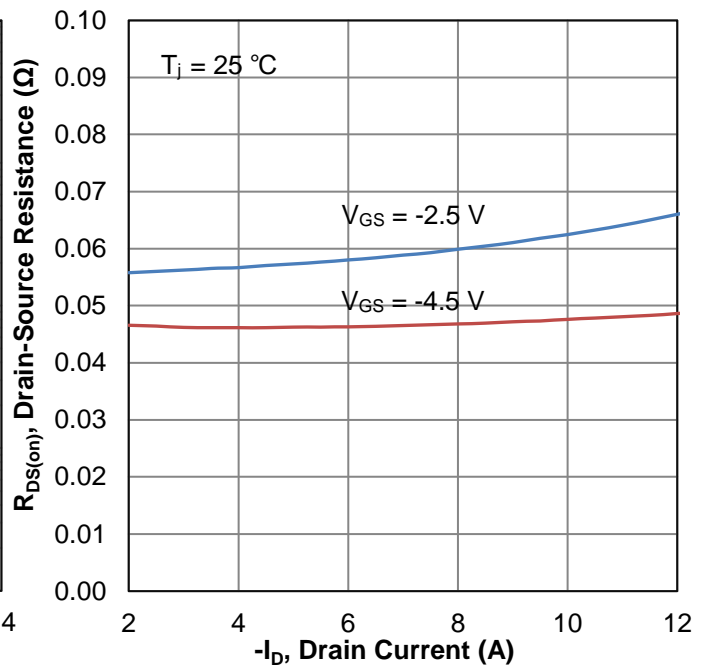


Figure 4. $R_{DS(on)}$ vs. $-I_D$

7. ELECTRICAL CHARACTERISTICS CURVES(Con.)

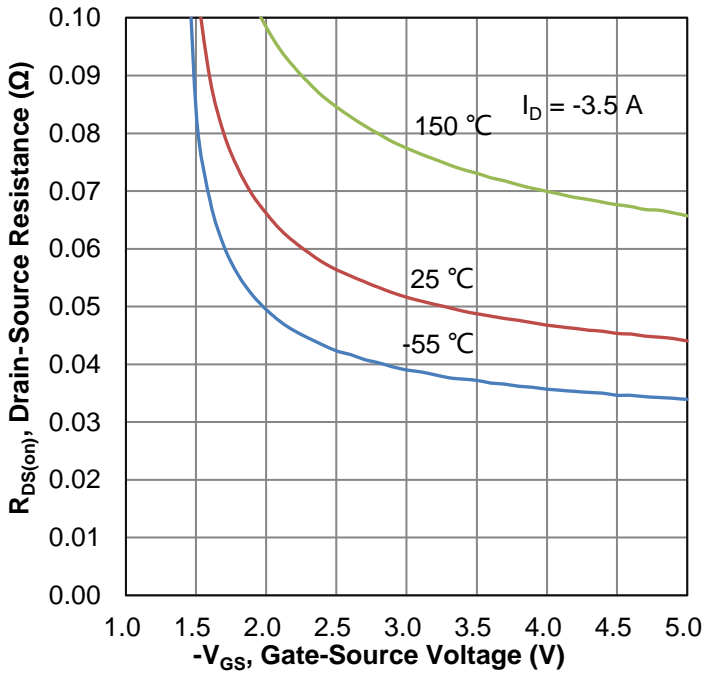


Figure 5. $R_{DS(on)}$ vs. $-V_{GS}$

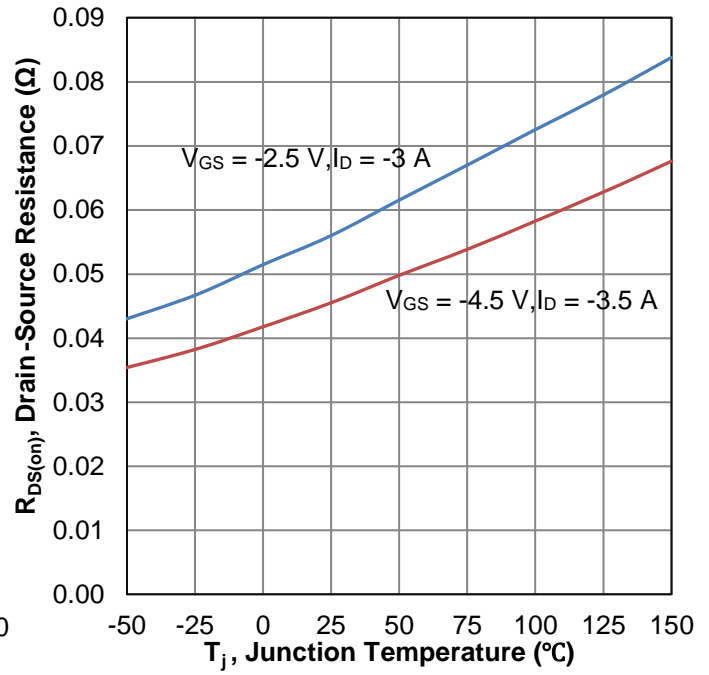


Figure 6. $R_{DS(on)}$ vs. T_j

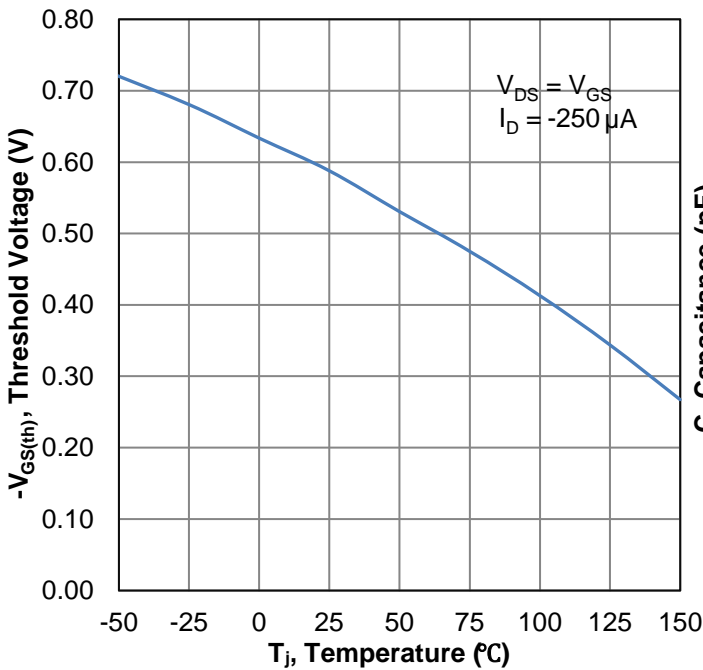


Figure 7. $-V_{GS(th)}$ vs. T_j

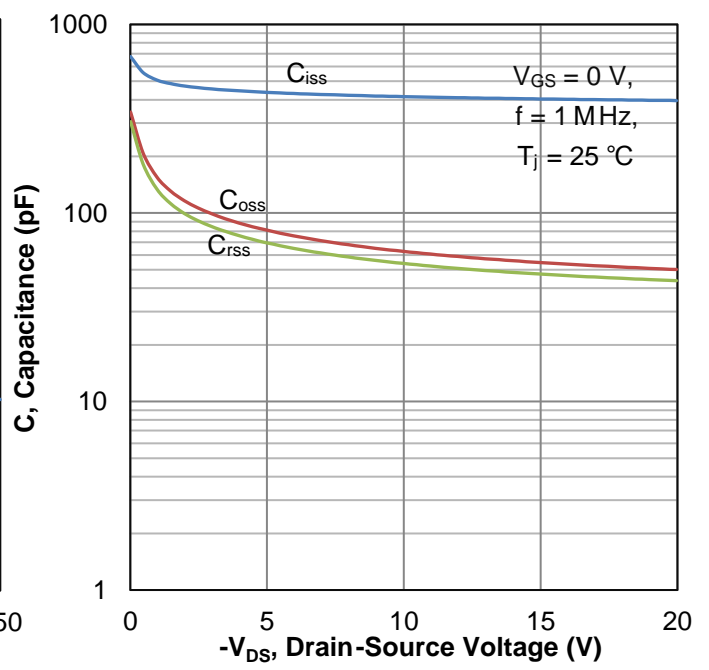


Figure 8. Capacitance

7. ELECTRICAL CHARACTERISTICS CURVES(Con.)

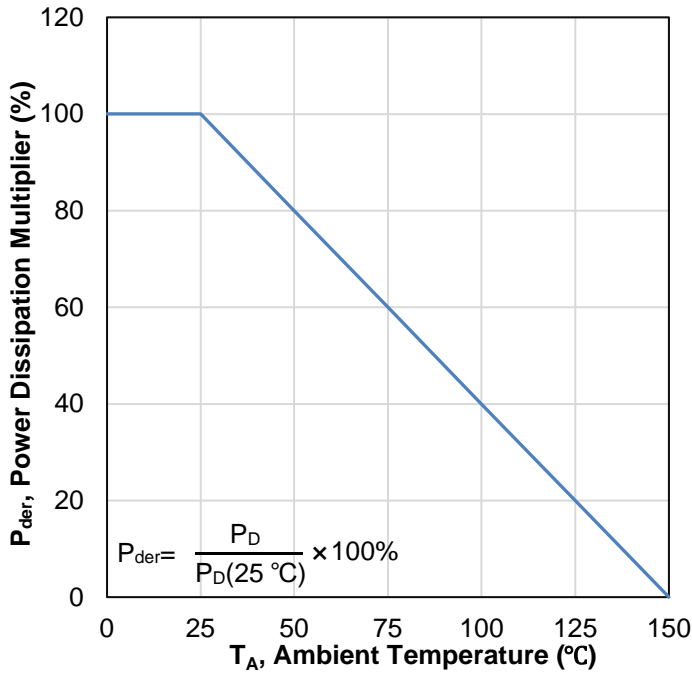


Figure 9. Normalized Derating Curve

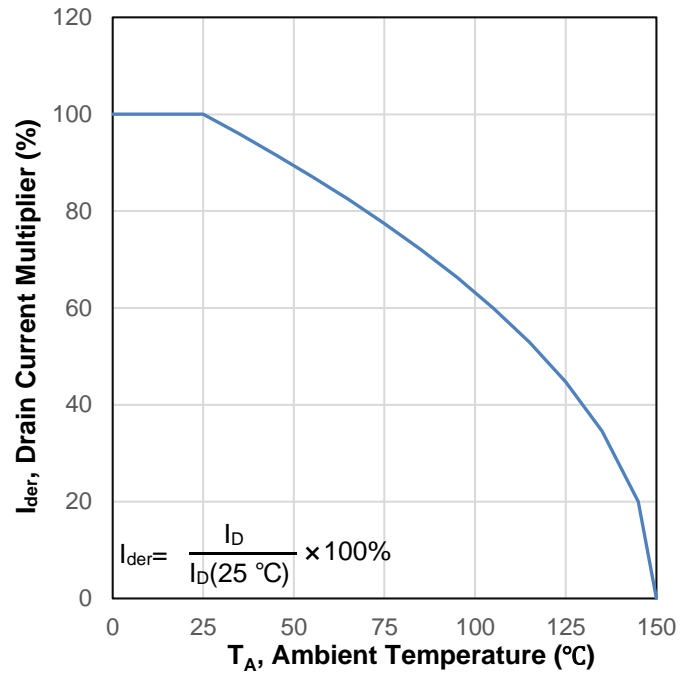


Figure 10. Normalized Drain Current

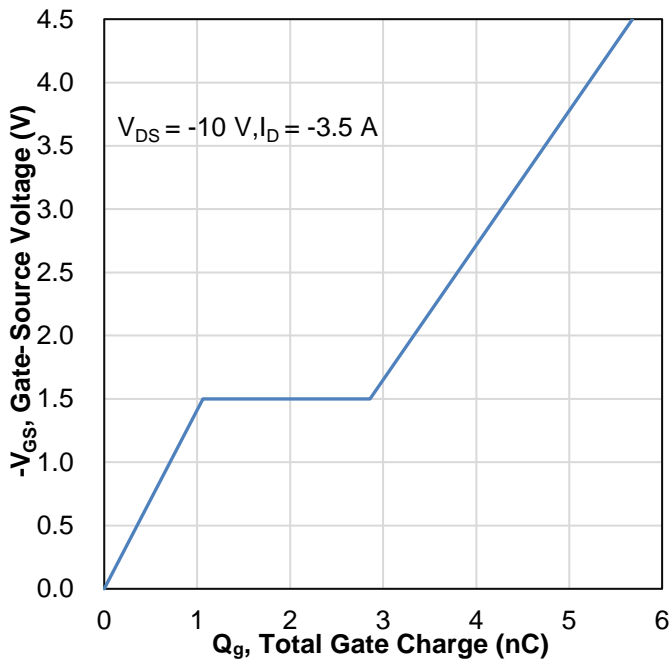


Figure 11. $-V_{GS}$ vs. Q_g

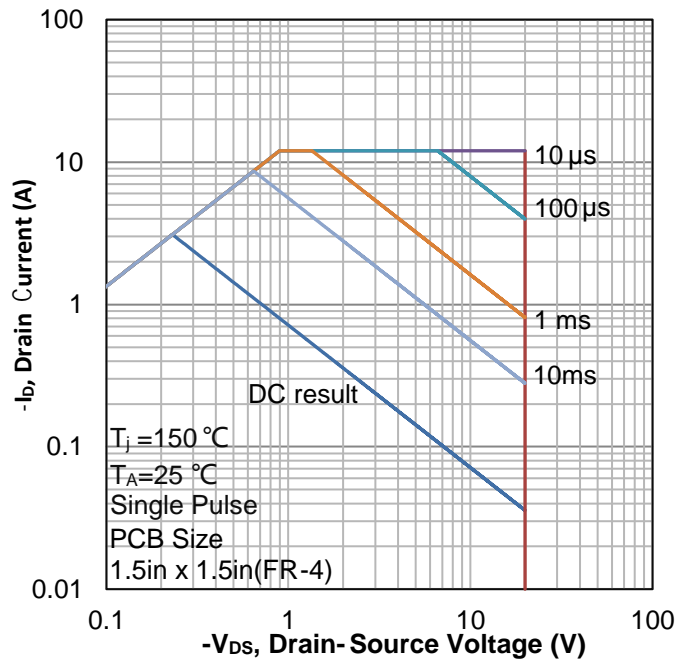
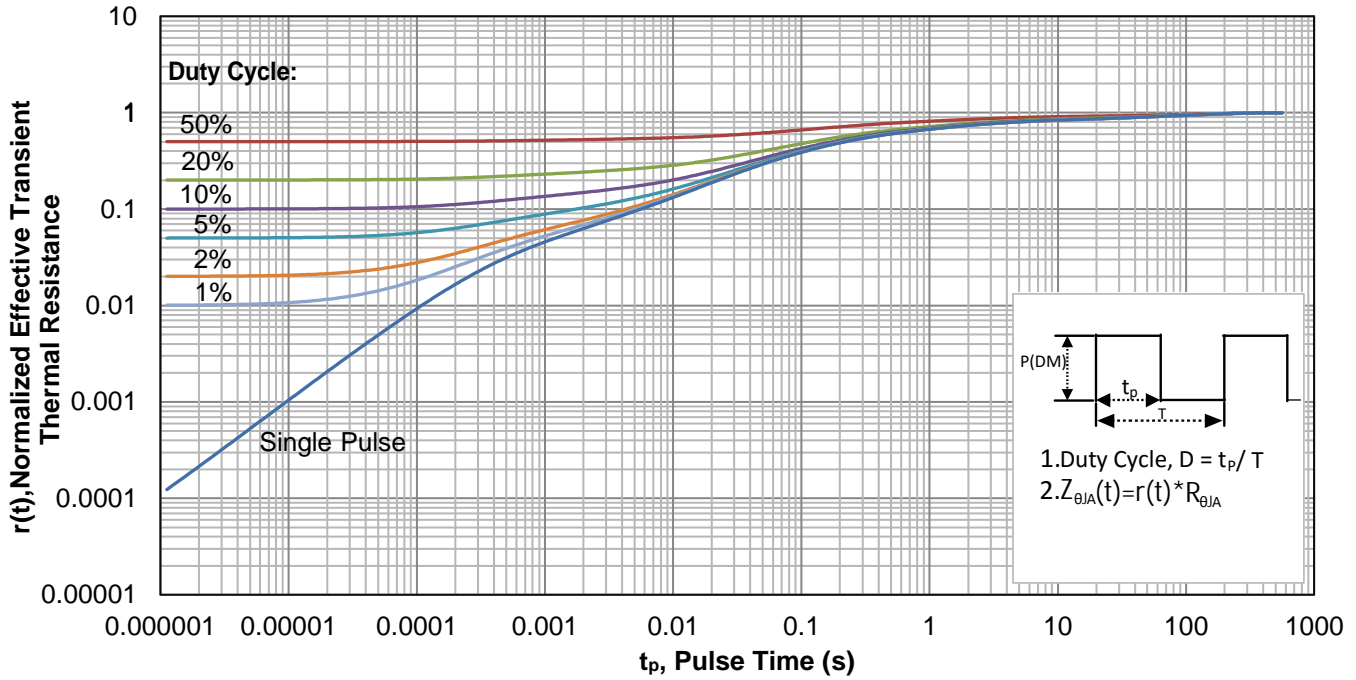
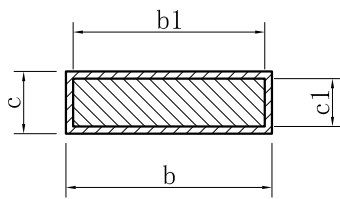
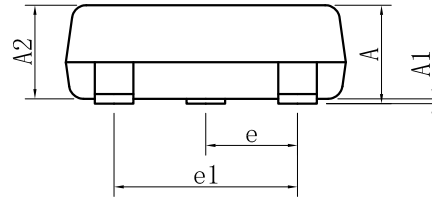
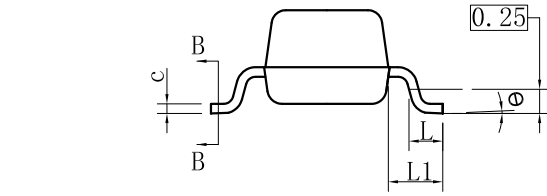


Figure 12. Safe Operating Area

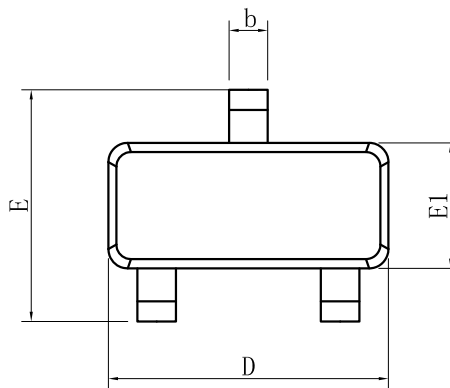
7. ELECTRICAL CHARACTERISTICS CURVES(Con.)



8. OUTLINE AND DIMENSIONS



SECTION B-B

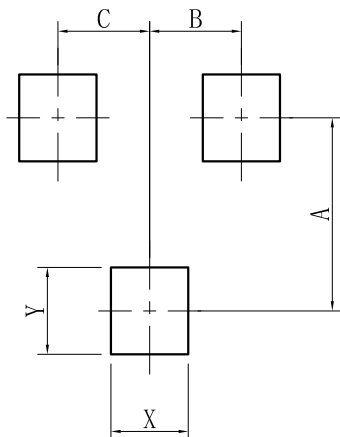


SOT23			
DIM	MIN	NOR	MAX
A	0.89	-	1.12
A1	0.01	-	0.10
A2	0.88	0.95	1.02
b	0.30	-	0.50
b1	0.30	0.40	0.45
c	0.08	-	0.20
c1	0.08	0.10	0.16
D	2.80	2.90	3.04
E	2.10	-	2.64
E1	1.20	1.30	1.40
e	0.95BSC		
e1	1.90BSC		
L	0.40	0.46	0.60
L1	0.54REF		
θ	0°	-	8°
All Dimensions in mm			

GENERAL NOTES

1. Top package surface finish Ra0.4±0.2um
2. Bottom package surface finish Ra0.7±0.2um
3. Side package surface finish Ra0.4±0.2um

9. SOLDERING FOOTPRINT



SOT23	
DIM	(mm)
X	0.80
Y	0.90
A	2.00
B	0.95
C	0.95

DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
- Before you use our Products for new Porject, you are requested to carefully read this document and fully understand its contents. LRC shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any LRC's Products against warning, caution or note contained in this document.
- All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using LRC's Products, please confirm the latest information with a LRC sales representative.